

# SP1250 50A Discrete Unidirectional TVS Diode











Note: This package image is for example and reference only. for detail package drawing, please refer to the package section in this datasheet.

#### **Description**

The SP1250 unidirectional TVS is fabricated in a proprietary silicon avalanche technology. These diodes provide a high ESD (electrostatic discharge) protection level for electronic equipment. The SP1250 TVS can safely absorb repetitive ESD strikes of ±30 kV (contact and air discharge as defined in IEC 61000-4-2) without any performance degradation. Additionally, each TVS can safely dissipate a 50A 8/20µs surge event as defined in IEC 61000-4-5 2nd edition.

#### **Pinout**

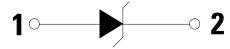
# SOD882



#### **Features**

- ESD, IEC 61000-4-2, ±30kV contact, ±30kV air
- EFT, IEC 61000-4-4, 40A (5/50ns)
- Lightning, 50A (8/20µs as defined in IEC 61000-4-5 2<sup>nd</sup> edition)
- · Low leakage current of 0.02µA (TYP) at 5V
- Halogen free, lead free and RoHS compliant
- Moisture Sensitivity Level (MSL-1)

#### **Functional Block Diagram**



#### **Applications**

- VBUS Protection
- Portable Battery
- Switches / Buttons
- Test Equipment / Instrumentation
- Medical Equipment
- Notebooks / Desktops / Servers
- Computer Peripherals
- Point-of-Sale Terminals

#### Life Support Note:

#### Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.



## **Absolute Maximum Ratings**

Symbol	Parameter	Value	Units
l <sub>pp</sub>	Peak Current (t <sub>p</sub> =8/20µs)	50	А
T <sub>OP</sub>	Operating Temperature	-40 to 125	°C
$T_{STOR}$	Storage Temperature	-55 to 150	°C

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

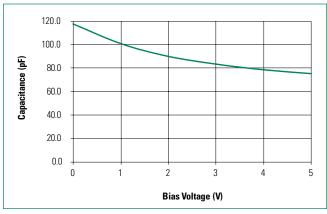
## Electrical Characteristics (T<sub>OP</sub>=25°C)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Reverse Standoff Voltage	V <sub>RWM</sub>	I <sub>R</sub> =1µA	-	-	5	V
Breakdown Voltage	V <sub>BR</sub>	I <sub>R</sub> =1mA	5.1	5.5	-	V
Reverse Leakage Current	LEAK	V <sub>R</sub> =5V	-	0.02	0.1	μА
Clamp Voltage <sup>1</sup>	V <sub>c</sub>	$I_{pp}=50A$ , $t_{p}=8/20\mu s$	-	8.7	10	V
Dynamic Resistance <sup>2</sup>	R <sub>DYN</sub>	TLP, t <sub>p</sub> =100ns	-	0.05	-	Ω
ESD Withstand Voltage <sup>1</sup>	V <sub>ESD</sub> -	IEC 61000-4-2 (Contact Discharge)	±30	-	-	kV
		IEC 61000-4-2 (Air Discharge)	±30	-	-	kV
Diode Capacitance <sup>1</sup>	C <sub>IO-GND</sub>	Reverse Bias=0V, f=1MHz	-	120	-	pF

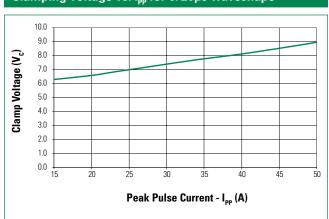
#### Note:

- 1. Parameter is guaranteed by design and/or component characterization.
- 2. Transmission Line Pulse (TLP) with 100ns width, 0.2ns rise time, and average window t1=70ns to t2= 90ns



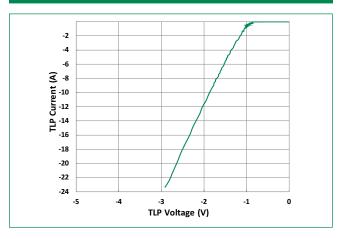


## Clamping voltage vs. I<sub>PP</sub> for 8/20µs waveshape

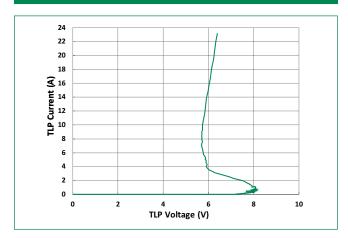




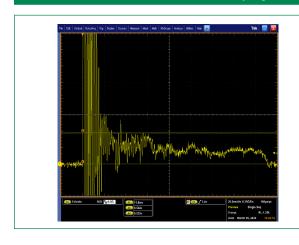
## **Negative Transmission Line Pulsing (TLP) Plot**



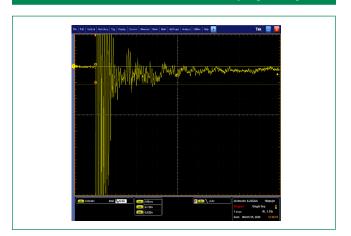
### Positive Transmission Line Pulsing (TLP) Plot



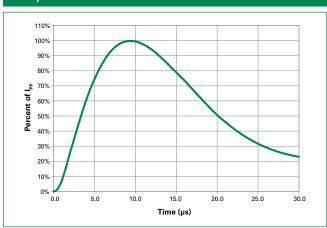
#### IEC 61000-4-2 +8 kV Contact ESD Clamping Voltage



### IEC 61000-4-2 -8 kV Contact ESD Clamping Voltage



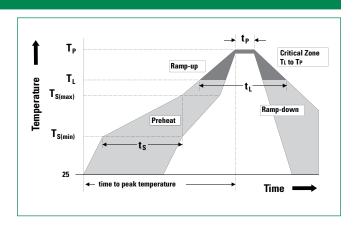
### 8/20µs Pulse Waveform





## **Soldering Parameters**

Reflow Cond	Pb – Free assembly		
Pre Heat	-Temperature Min (T <sub>s(min)</sub> )	150°C	
	-Temperature Max (T <sub>s(max)</sub> )	200°C	
	-Time (min to max) (t <sub>s</sub> )	60 – 180 secs	
Average ram	3°C/second max		
T <sub>S(max)</sub> to T <sub>L</sub> -	3°C/second max		
Reflow	-Temperature (T <sub>L</sub> ) (Liquidus)	217°C	
	-Temperature (t <sub>L</sub> )	60 – 150 seconds	
Peak Temper	260 <sup>+0/-5</sup> °C		
Time within	20 - 40 seconds		
Ramp-down	6°C/second max		
Time 25°C to	8 minutes Max.		
Do not exce	260°C		



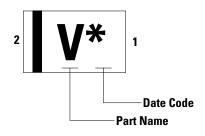
# Ordering Information

Part Number	Package	Min. Order Qty.
SP1250-01ETG	SOD882	10,000

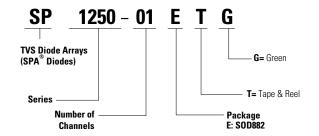
#### **Product Characteristics**

Lead Plating	Matte Tin		
Lead material	Copper Alloy		
Substrate Material	Silicon		
Body Material	Molded Compound		
Flammability	UL Recognized compound meeting flammability rating V-0		

## **Part Marking System**

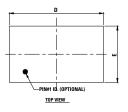


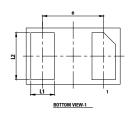
## **Part Numbering System**





### Package Dimensions — SOD882





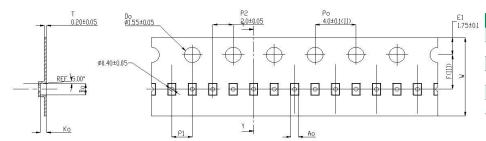
	SOD882					
Symbol	ı	Millimeters	\$	Inches		
	Min	Тур	Max	Min	Тур	Max
Α	0.40	0.50	0.55	0.016	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
L1	0.20	0.25	0.30	0.008	0.010	0.012
L2	0.45	0.50	0.55	0.018	0.020	0.022
D	0.95	1.00	1.05	0.037	0.039	0.041
E	0.55	0.60	0.65	0.022	0.024	0.026
е	0.65 BSC				0.026 BSC	



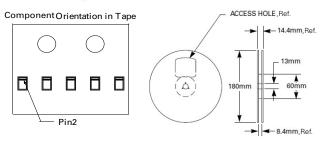


Drawing# : E03-B

**Embossed Carrier Tape & Reel Specification — SOD882** 



Symbol	Millimeters		
A0	0.70+/-0.045		
В0	1.10+/-0.045		
K0	0.65+/-0.045		
F	3.50+/-0.05		
P1	2.00+/-0.10		
W	8.00 + 0.30 -0.10		



8mm TAPE AND REEL

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